

EAST 4

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	("5741598").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/26 10:04
S3	4388	storage near modulus	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 11:09
S4	159302	polyimide	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 10:04
S5	75	S3 same S4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 11:11
S6	0	("2002/0086171").URPN.	USPAT	OR	ON	2006/01/26 10:26
S7	30808	(young or "young's" or youngs) near modulus	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 15:46
S8	956	S4 same S7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 10:36
S9	43	S8 same (glass near transition)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 10:48
S10	6	("20010031828"   "5241041"   "5932345"   "6350844"   "6538093"   "6693162").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/26 10:34

S11	447	S4 near10 S7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 10:37
S14	34889	S3 S7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 10:48
S16	105213	(glass near transition)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 10:48
S17	1515	S14 same S16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 12:28
S18	46	S17 same (insulate or insulated or insulating)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 10:49
S19	472638	(printed or circuit) near3 board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 10:59
S23	96594	(storage near modulus) or ((young or "young's" or youngs) near modulus) or ((elastic or elasticity) near3 modulus)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 11:10
S24	284	((resin or adhesive or glue or binder) near10 (S23 near10 (pa or mpa or gpa))) and S19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 11:10

S27	3757	S23 same S16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 12:28
S28	424	S19 and S27	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 13:12
S29	15766	peel near strength	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 13:12
S31	240	S23 same S29	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 15:21
S32	3	("5262227"   "5741598"   "6203918").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/26 15:18
S33	9	("5741598").URPN.	USPAT	OR	ON	2006/01/26 15:19
S34	5	S33 and modulus	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 15:21
S36	86	adhesive with (low near2 modulus) with (high near2 strength)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 15:46
S37	30	"0157112"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/27 08:03
S38	54	"0100549"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/27 08:03

S39	3	adhesive near polyimide near resin near2 adhesive near laminate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/27 08:04
S40	23	polyimide and tokuhisa and nippon	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/27 08:13
S41	14	polyimide same "en-20"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/27 08:18
S44	20	polyimide and "paa-a"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/27 08:23
S45	148	(thermoplastic near polyimide) same modulus	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/27 10:02
S47	110	(copper or foil) same (photosensitive near resin) same ((pattern or patterned or patterning) near4 circuit)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/27 10:05
S48	28	(copper or foil) near10 (photosensitive near resin) near10 ((pattern or patterned or patterning) near4 circuit)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/27 10:12
S49	9	("3227553"   "3492151"   "3562005"   "3615457"   "3647450"   "3719490").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/27 10:08
S50	9	("3840390"   "3952023"   "4023973"   "4033840"   "4382128"   "4401793"   "4508874"   "4673458"   "4877818").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/27 10:09

S51	24	(copper or foil) same (photosensitive near resin) same mask same ((pattern or patterned or patterning) near4 circuit)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/27 10:47
S52	53	(copper or foil) same (photosensitive near resin) same mask same (etch or etching or etched) same circuit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/27 10:19
S53	255	(photo near (etch or etched or etching)) same ((pattern or patterned or patterning) near5 circuit)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/27 10:19
S54	117	(photosensitive near resin) same mask same ((pattern or patterned or patterning) near4 circuit)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/27 10:52
S55	100	S54 not S52	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/27 10:48
S56	2	("4325780"   "4487654").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/27 10:49
S58	244	(photosensitive near resin) near10 ((pattern or patterned or patterning) near4 circuit)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/27 10:56
S59	190	S58 not S54	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/27 10:52
S60	4251	(photosensitive near resin) and polyimide	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/27 10:56

S61	63	(photosensitive near resin) and (thermoplastic near polyimide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/27 10:59
S63	56	(photosensitive near20 mask near20 dissolve)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/27 11:01
S64	45	((photo near (etch or etching or etched)) same circuit).ti.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/27 11:02
S68	6692	((156/299,308.2) or (428/458)). CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/27 11:28
S69	504	S68 and modulus	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/27 11:29
S70	144	S68 and (thermoplastic near20 polyimide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/27 11:36